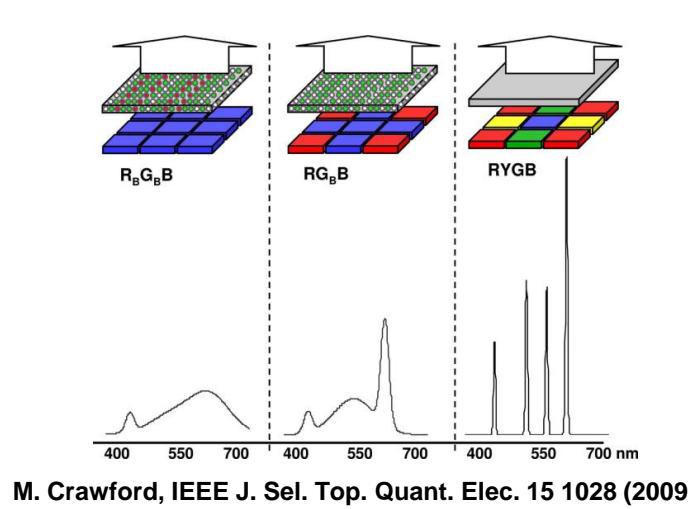
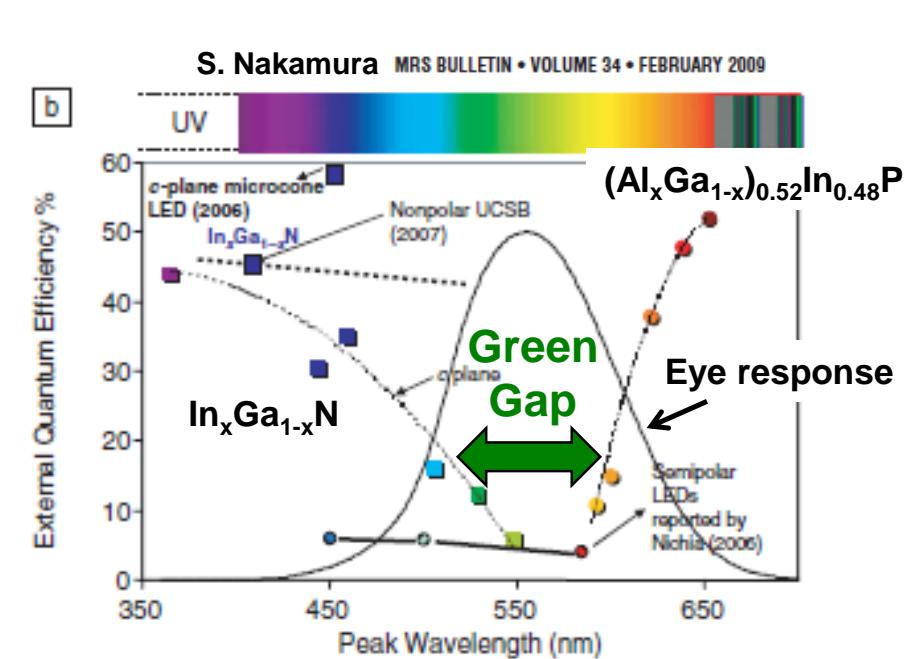


Goal: Increase EQE of InGaN 540 nm LEDs through defect reduction

Objective: Increase efficiency of deep green-emitting InGaN/GaN LEDs through InGaN defect reduction



M. Crawford, IEEE J. Sel. Top. Quant. Elec. 15 1028 (2009).
Multichip LEDs promise better efficiency than phosphor-converted LEDs, but...



Goal: Mitigate InGaN defects in InGaN/GaN MQWs
Challenge: Develop *quantitative* defect spectroscopy for In_{0.2}Ga_{0.8}N epilayers

Major Project Milestones:

- Develop quantitative defect spectroscopy for nanoscale In_xGa_{1-x}N films
- Reduce defect incorporation and improve EQE for 540 nm InGaN QWs
- Improve EQE for 540 nm InGaN LEDs via reduced defect incorporation

Problems to be addressed:

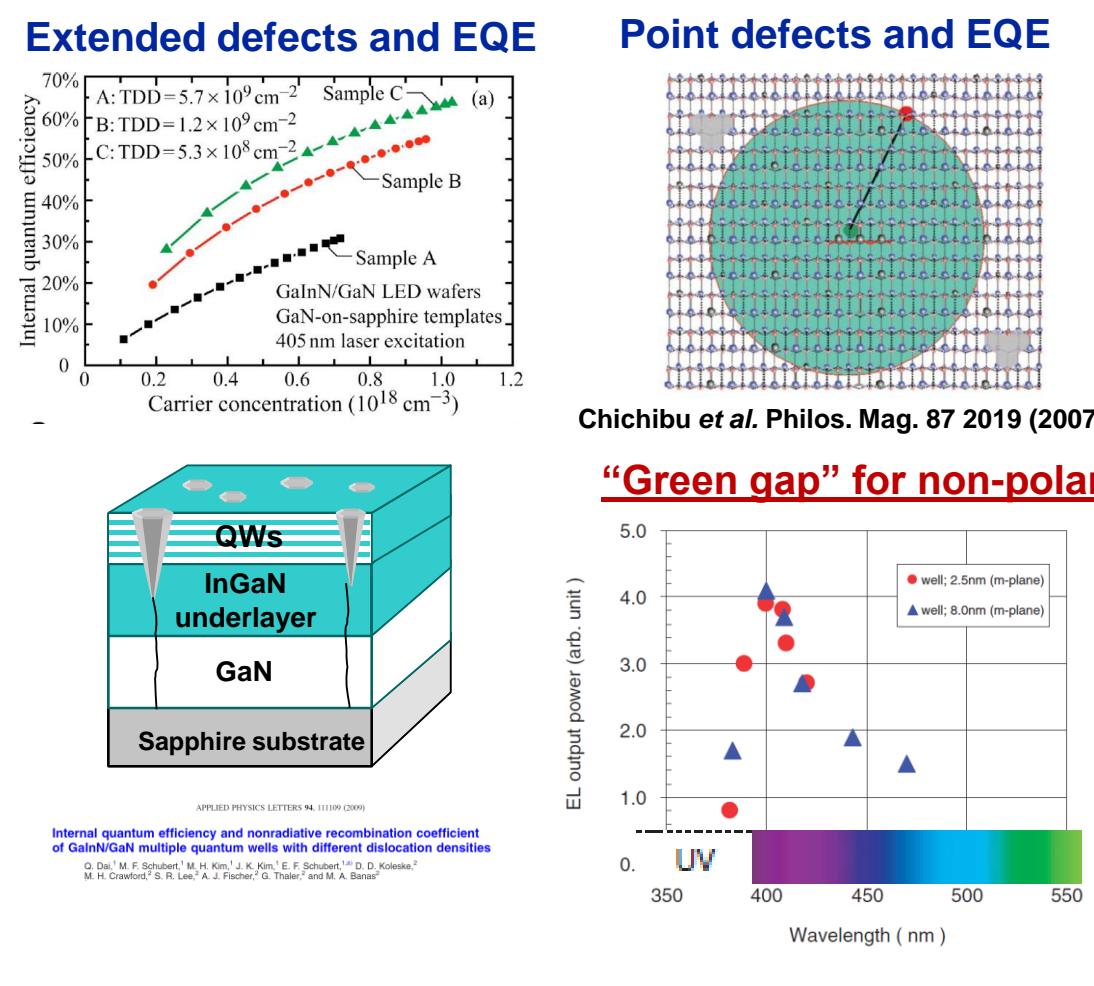
- Understand In_xGa_{1-x}N ($x > 0.15$) deep level defect activity
- Correlate defect incorporation and In_xGa_{1-x}N growth parameters
- Determine impact of defects on LED External Quantum Efficiency (EQE)

Expected Benefits to SSL:

- Enhanced EQE of (540 nm) LEDs
- Increase both luminous efficiency and CRI for RGB color-mixing
- Accelerate white SSL penetration into lighting market

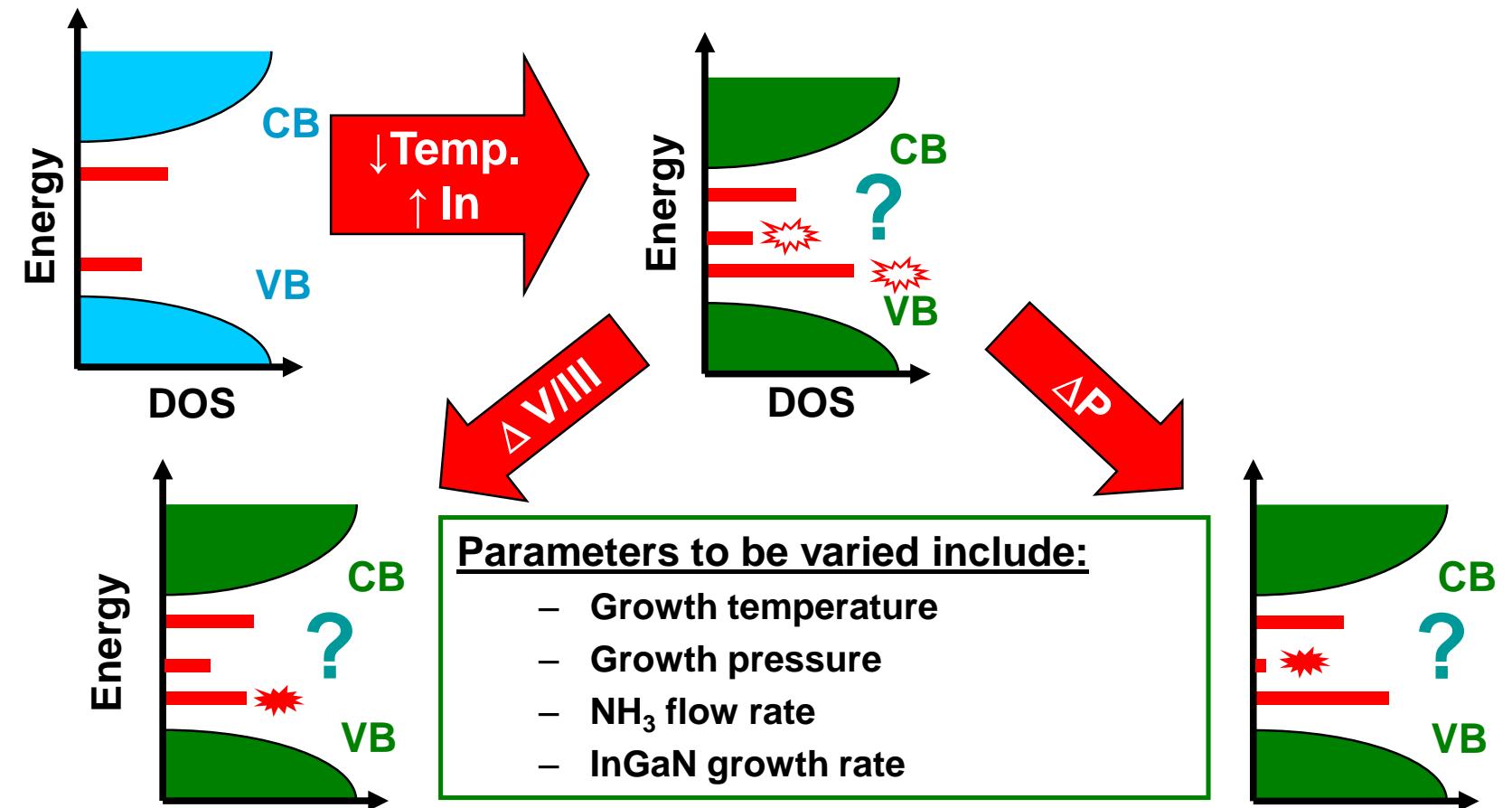
Impact of InGaN Defects on Efficiency

Impact of defects on radiative efficiency



- How to connect InGaN growth conditions, defects and EQE?
- Solution: Adapt Deep Level Optical Spectroscopy for InGaN LEDs

Systematic study of InGaN defects



- Need method to *quantify* deep level defect energy and density
- Correlate defect studies with EQE
- Vary growth parameters to mitigate critical defects and improve EQE

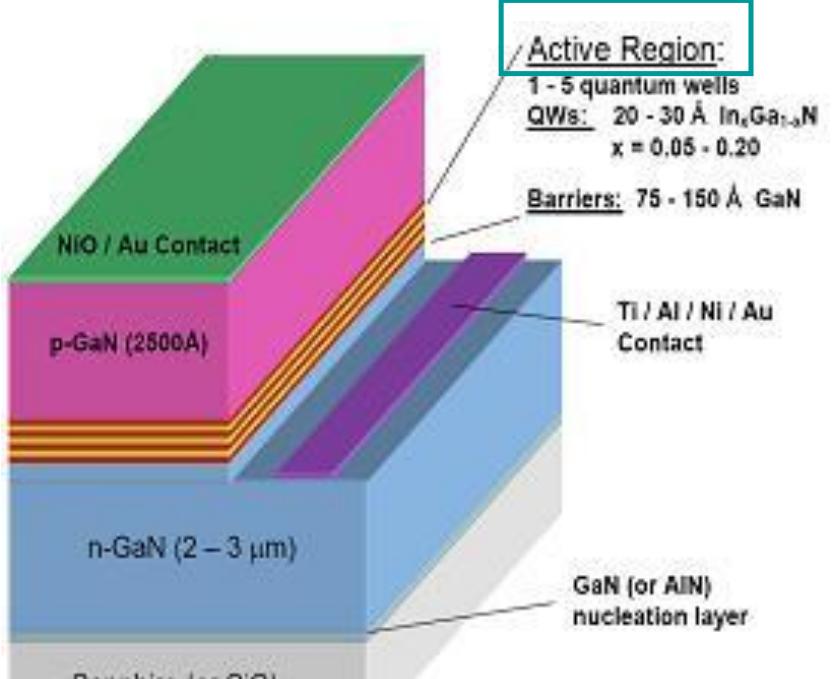
Challenge and Solution

Problem: How to study InGaN LED defects?

LEDs are complicated nanoscale, multi-heterolayer, bipolar devices with strongly varying (In,Al,Ga)N alloy compositions

Defects located near the optically active MQW region are most critical to LED radiative efficiency

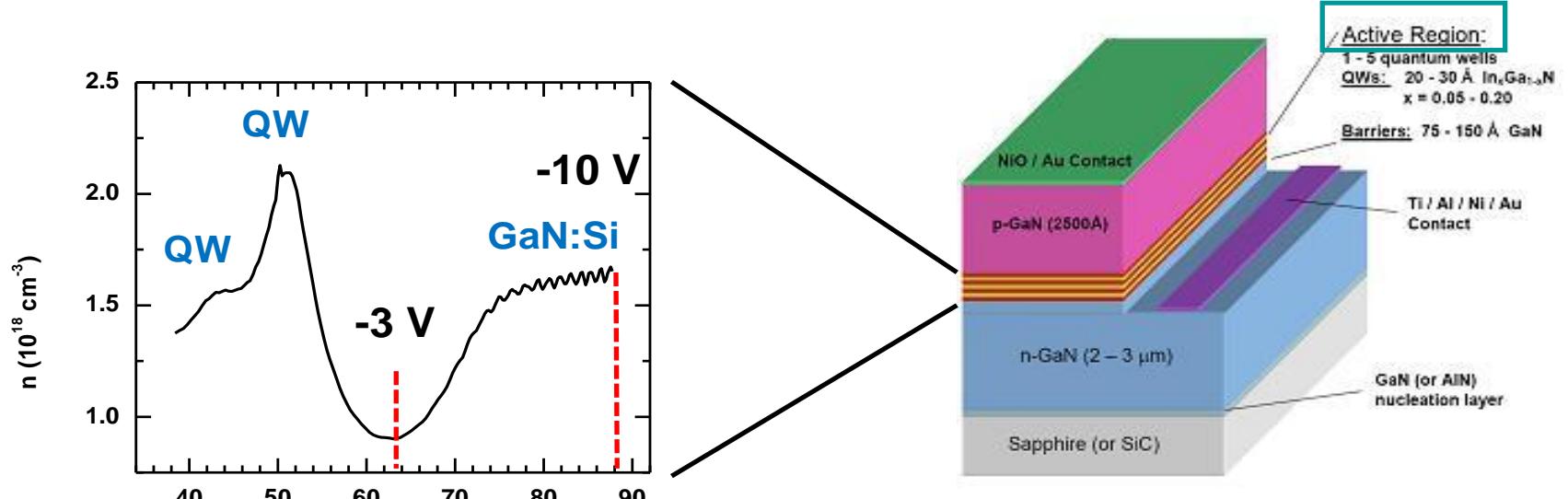
How to isolate and study defects in the nanoscopic MQW region embedded in a microscopic LED?



Solution: Depth-resolved Deep Level Optical Spectroscopy

Deep Level Optical Spectroscopy (DLOS)

- Photocapacitance technique
 - Sub-band gap optical stimulation to photoionize defect levels (reverse of PL)
 - Quantify non-radiative defect level energy and density (difficult for PL)
 - Depletion region technique for *depth resolution*



- DLOS depth resolution from pin LED junction
- Junction contains the MQW region and the n-GaN region
- Use electrical bias to emphasize defects in either the MQW or n-GaN regions

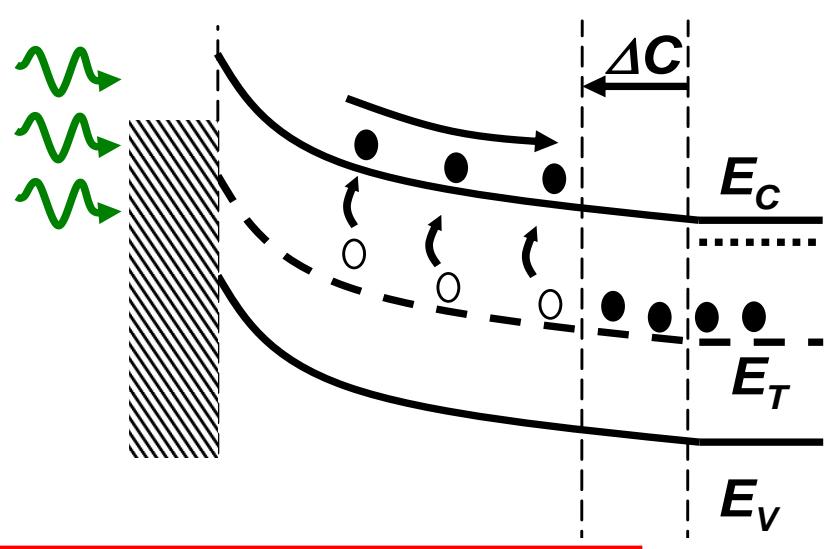
Concept of Depth-resolved DLOS

Fundamentals of DLOS

Sub-band gap, monochromatic light to scan defect states

Steady-state photocapacitance

- Depletion region technique
- ΔC indicative of N_i
- (+) onset \rightarrow Majority carrier emission
- (-) onset \rightarrow Minority carrier emission



Deep Level Optical Spectroscopy¹

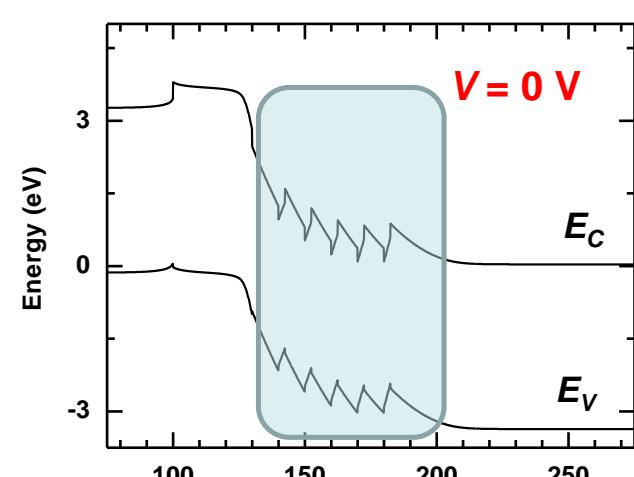
- Measures deep level optical cross-section σ^o :
 - $dC(t)/dt|_{t=0} \propto \sigma^o(h\nu)\Phi(h\nu)$
- Fitting $\sigma^o(h\nu)$ to model² extracts deep level defect properties
 - Optical ionization energy E^o
 - Franck-Condon shift d_{FC} (a measure of defect-phonon coupling)

DLOS and SSPC Measurement Conditions

- Xe lamp and monochromator for $h\nu = 1.20 - 3.60$ eV, 20 meV resolution
- 297 K, various fill and reverse biases for depth sensitivity
- Lock-in amplifier at 5 kHz

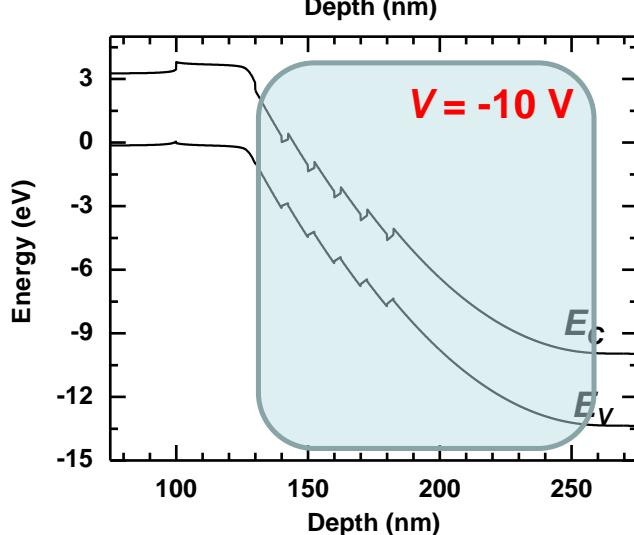
1. Chantre *et al.* PRB 23, 5335 (1981). 2. Paessler JAP 96, 715 (2004).

Depth-resolved LED DLOS



$V = 0$ V: DLOS "sees" mostly the MQW region

- Detect InGaN well and GaN barrier defects



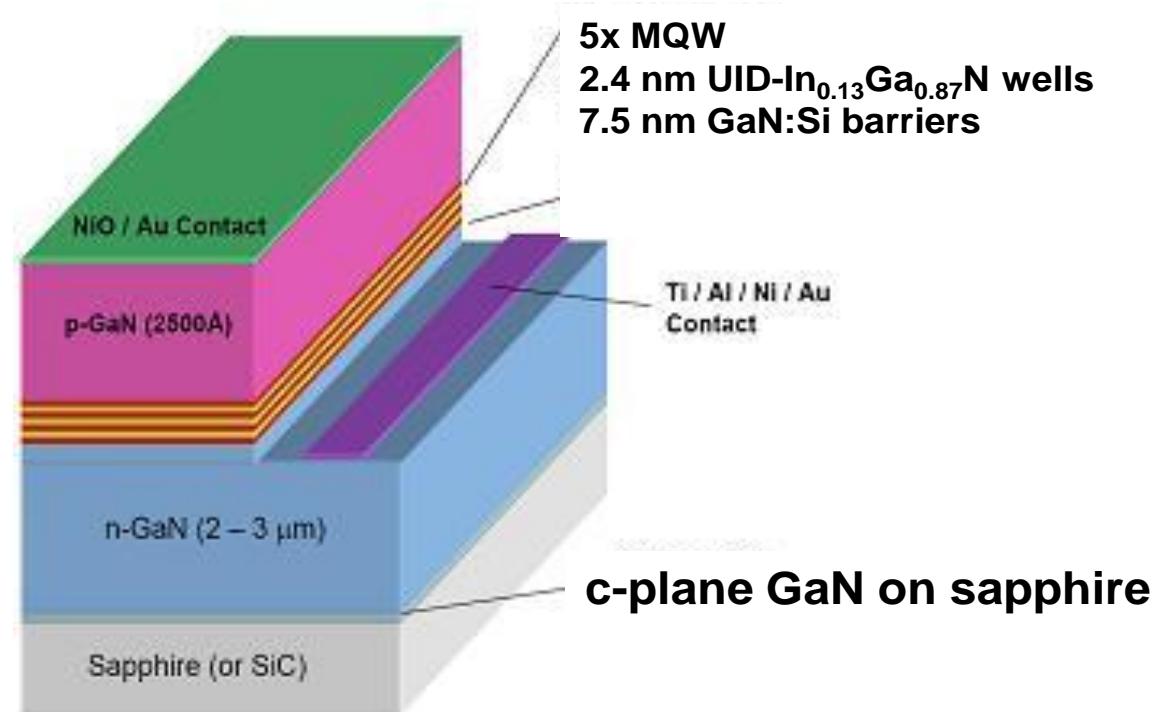
$V = -10$ V: DLOS "sees" MQW and n-GaN region

- Weak sensitivity to InGaN well defects
- Strong sensitivity to GaN defects

DLOS at small and large reverse bias discerns GaN vs. InGaN defects in LEDs

Test case – Impact of Dislocations on InGaN/GaN LED EQE

InGaN/GaN LED structure



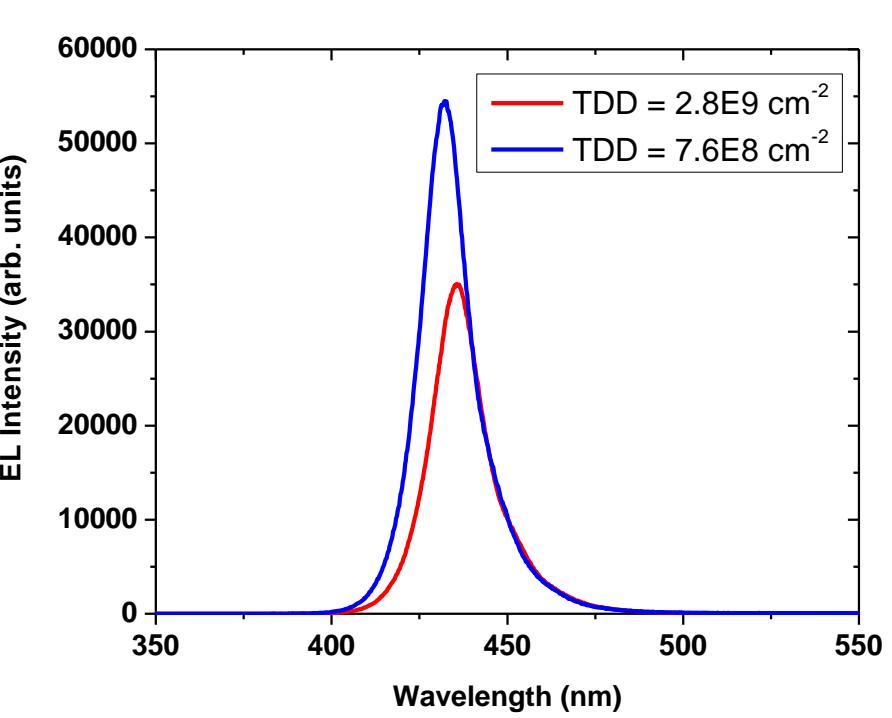
- MOCVD grown
- Threading dislocation density (TDD) $\sim 7.6 \times 10^8 \text{ cm}^{-2}$ or $2.8 \times 10^9 \text{ cm}^{-2}$
- TDD controlled by GaN nucleation and coalescence parameters¹
- TDD measured via x-ray diffraction rocking curve analysis²

1. M. F. Schubert, S. Chibed, J. K. Kim, E. F. Schubert, D. D. Koleske, M. J. Crawford, S. R. Lee, A. J. Fischer, G. Thaler, and M. A. Banas, *Appl. Phys. Lett.*, **91**, 231114 (2007).

2. S. R. Lee, A. M. West, A. A. Allerman, K. E. Waldrip, D. M. Follstaedt, P. P. Provencio, D. D. Koleske, and C. R. Abemathy, *Appl. Phys. Lett.*, **86**, 241904 (2005).

LED characterization

TDD vs. EL for on-chip test devices

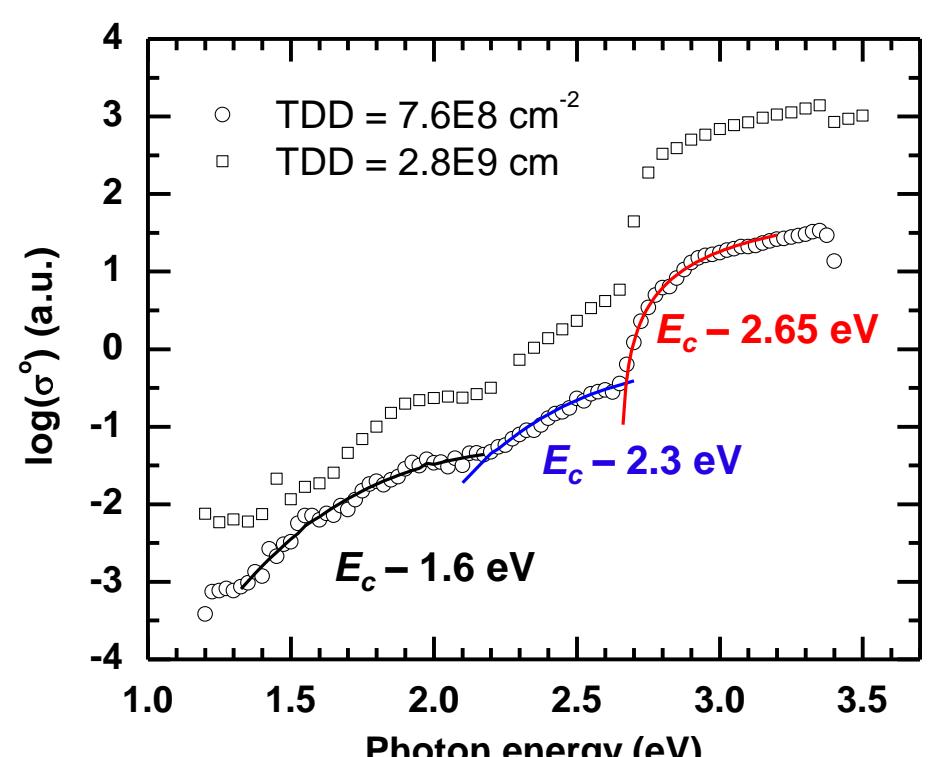


- 50% improved integrated electroluminescent (EL) intensity for lower TDD
- Relative EL intensity of on-chip test devices indicative of relative LED EQE
- Consistent with earlier reports, but details TDD role on EL unknown...

MQW vs. n-region defects

Survey of LED MQW region defects

-3 V DLOS

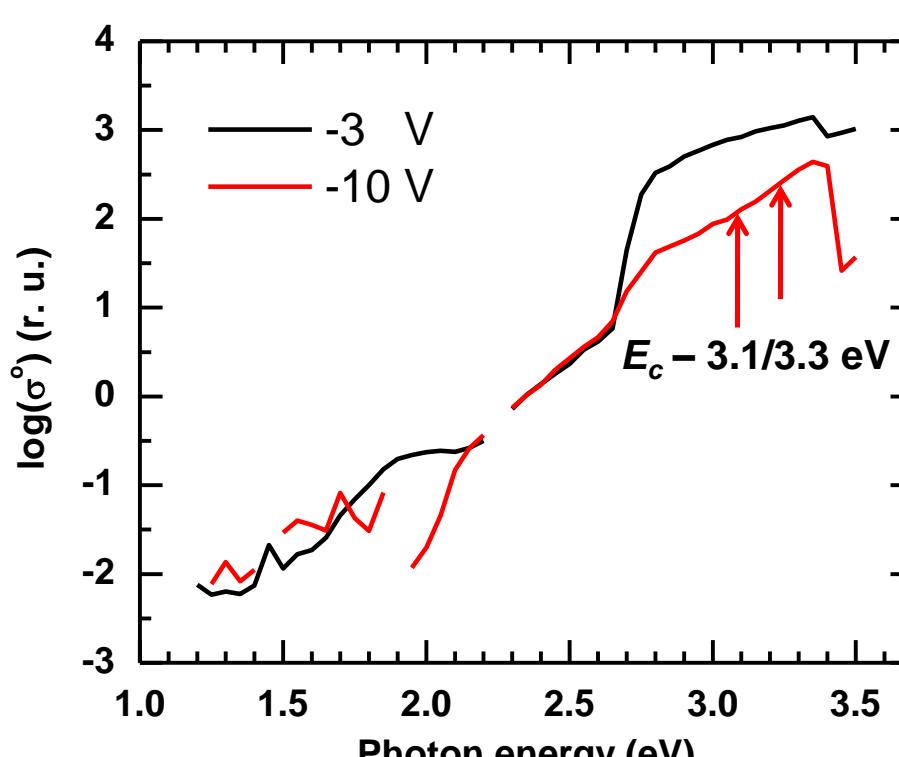


Observe three defect states in MQW region:

- Similar defect states for both samples – no new defects with increased TDD
- $E_c - 2.65$ eV likely InGaN-related due to proximity to InGaN band edge
- Location of remaining defect levels unclear

Survey of n-region defects

-3 V (MQW) vs. -10 V (MQW + n-region) DLOS

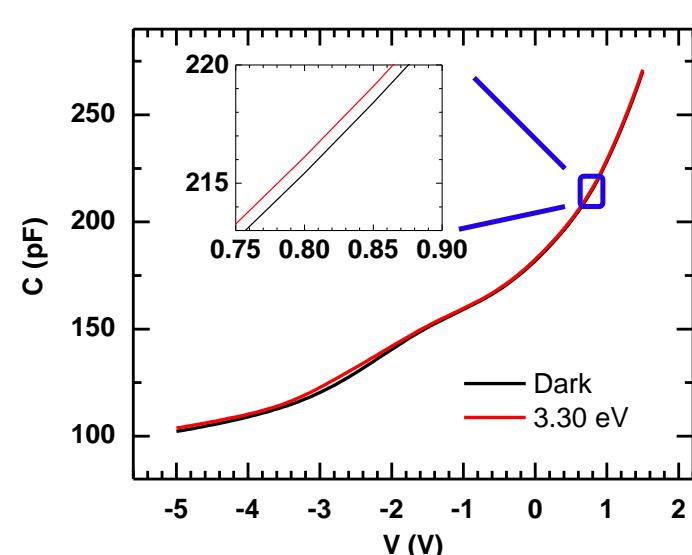


- New GaN-related defect levels at $E_c - 3.1/3.3$ eV
- $E_c - 2.3$ eV level still evident – likely GaN-related
- No $E_c - 1.6$ eV level – likely InGaN-related

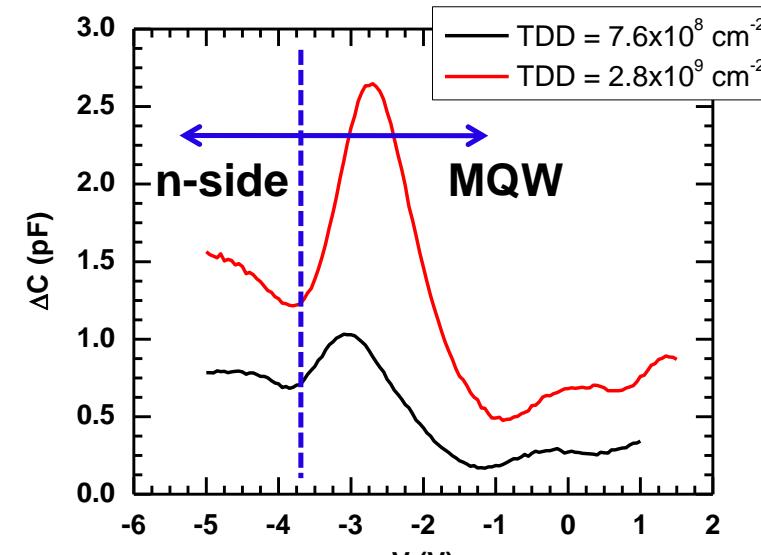
Impact of TDD on Defect Density

Measuring LED defect density

Lighted C-V for TDD = $7.6 \times 10^8 \text{ cm}^{-2}$



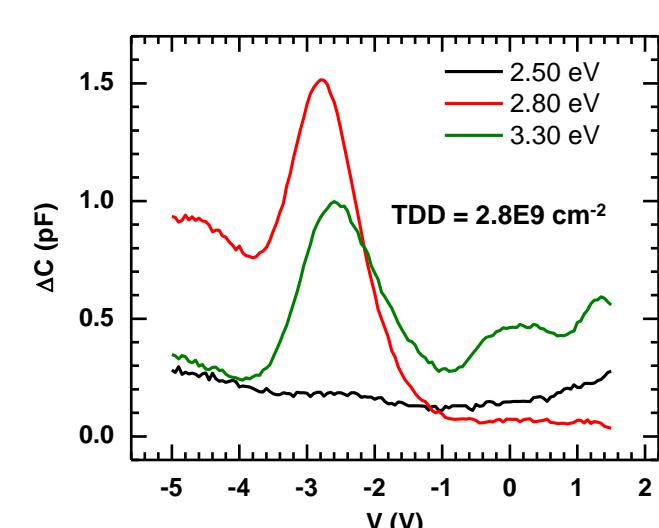
LCV comparison vs. TDD



Lighted Capacitance-Voltage (LCV) measurements quantify defect density (N_t)
➤ Area under C-V curve proportional to space-charge density in LED junction
➤ Increase in capacitance with light (ΔC) results from defect photoionization
➤ Calculate average N_t from area under LCV curve

LED defect density vs. TDD

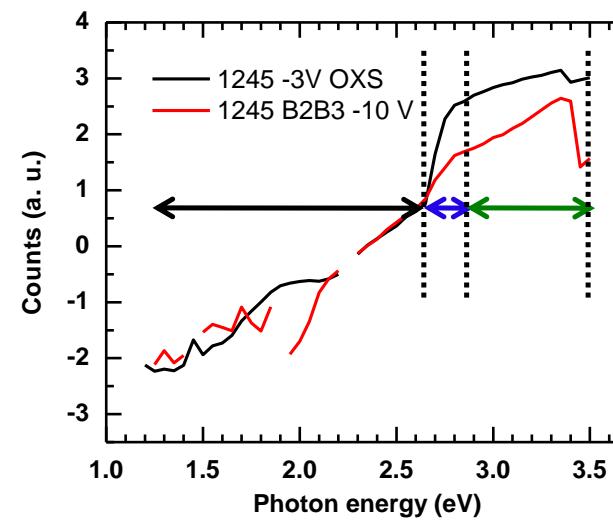
LCV for individual defect states



Average N_t for MQW-region defect states

Defect Level (eV)	TDD = $7.6 \times 10^8 \text{ cm}^{-2}$ (N_t in cm^{-3})	TDD = $2.8 \times 10^9 \text{ cm}^{-2}$ (N_t in cm^{-3})	ΔN_t
$E_c - 1.6/2.3$	8.8×10^{14}	3.2×10^{15}	$3.6x$
$E_c - 2.65$	1.8×10^{16}	3.2×10^{16}	$1.8x$
$E_c - 3.1/3.3$	3.7×10^{15}	1.4×10^{16}	$4x$

➤ Strong decrease in N_t with reduced N_t for both InGaN- and GaN-related defects
➤ Universal decrease in N_t suggests TDD impacts both point and extended defect density incorporation in LEDs



Summary and Outlook

Summary and Future Work

➤ First quantitative defect spectroscopy for InGaN LEDs
➤ Reducing TDD reduces point and extended defect incorporation in InGaN/GaN LEDs
➤ 50% enhancement of LED radiative efficiency with defect reduction

➤ Extend DLOS study to blue- and green-emitting LEDs
➤ Identify defects that correlate with reduced EQE with increase wavelength
➤ Systematic reduction in targeted defects to improve InGaN/GaN LED EQE at 540 nm

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